

## 1. General description

Ultrafast, epitaxial rectifier diode in a SOD59 (TO-220AC) plastic package

## 2. Features and benefits

- Fast switching
- Low thermal resistance
- Soft recovery characteristic
- Low forward voltage drop
- Low switching loss
- High thermal cycling performance

## 3. Applications

- Output rectifiers in high frequency switched-mode power supplies
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_R$	reverse voltage	Square-wave; $\delta = 1.0$	600			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_{mb} \leq 108\text{ °C}$ ; Square-wave pulse; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	15			A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\ \mu\text{s}$ ; $T_{mb} \leq 108\text{ °C}$ ; Square-wave	30			A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ °C}$ ; Sinusoidal waveform; <a href="#">Fig. 4</a>	130			A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ °C}$ ; Sinusoidal waveform	143			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 15\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 6</a>	-	1.17	1.38	V
		$I_F = 15\text{ A}$ ; $T_j = 150\text{ °C}$ ; <a href="#">Fig. 6</a>	-	1	1.2	V
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}$ ; $V_R = 30\text{ V}$ ; $di_F/dt = 100\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>	-	50	60	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	mb	mounting base; cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYT79-600	TO-220AC	plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC	SOD59

## 7. Marking

Table 4. Marking codes

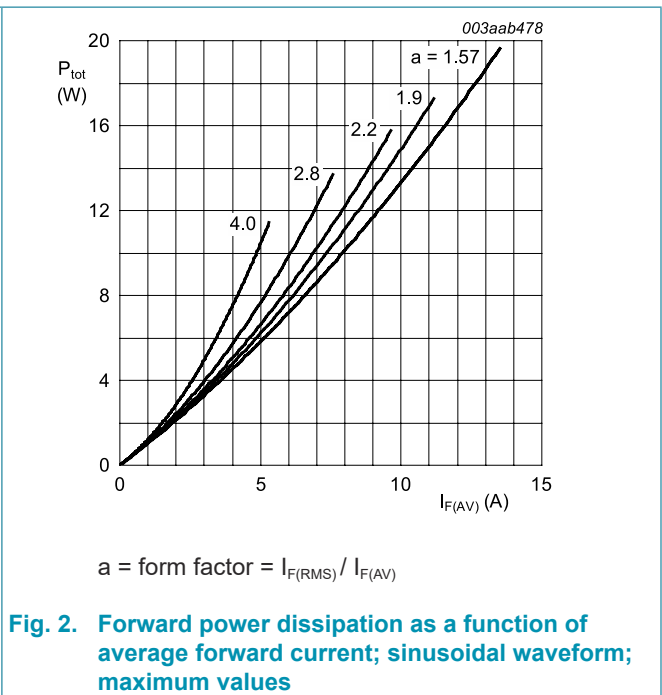
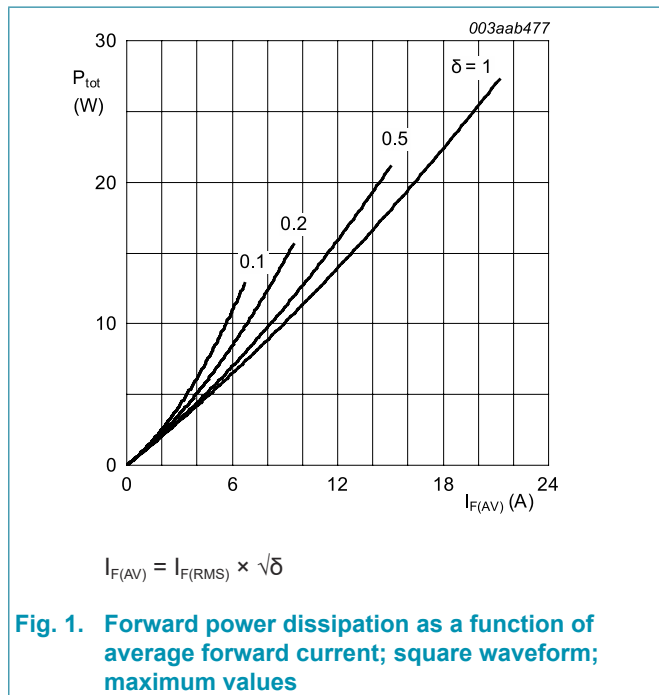
Type number	Marking codes
BYT79-600	BYT79-600

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		600	V
$V_{RWM}$	crest working reverse voltage		600	V
$V_R$	reverse voltage	Square-wave; $\delta = 1.0$	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_{mb} \leq 108\text{ }^\circ\text{C}$ ; square-wave pulse; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	15	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 108\text{ }^\circ\text{C}$ ; Square-wave	30	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; Sinusoidal waveform; <a href="#">Fig. 4</a>	130	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; Sinusoidal waveform	143	A
$T_{stg}$	storage temperature		-55 to 150	$^\circ\text{C}$
$T_j$	junction temperature		150	$^\circ\text{C}$



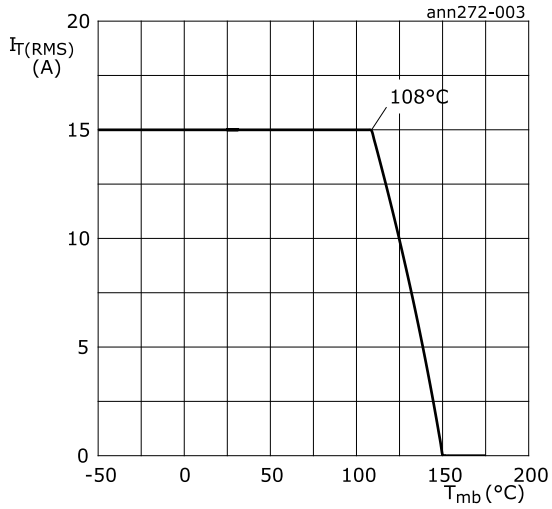


Fig. 3. RMS on-state current as a function of mounting base temperature; maximum values

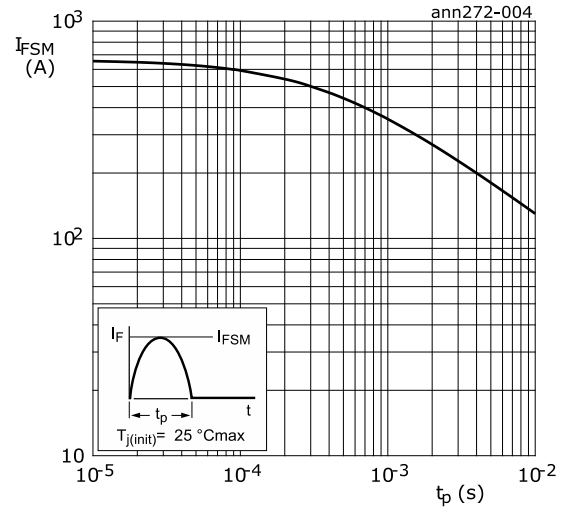


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; <a href="#">Fig.5</a>	-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air		-	60	-	K/W

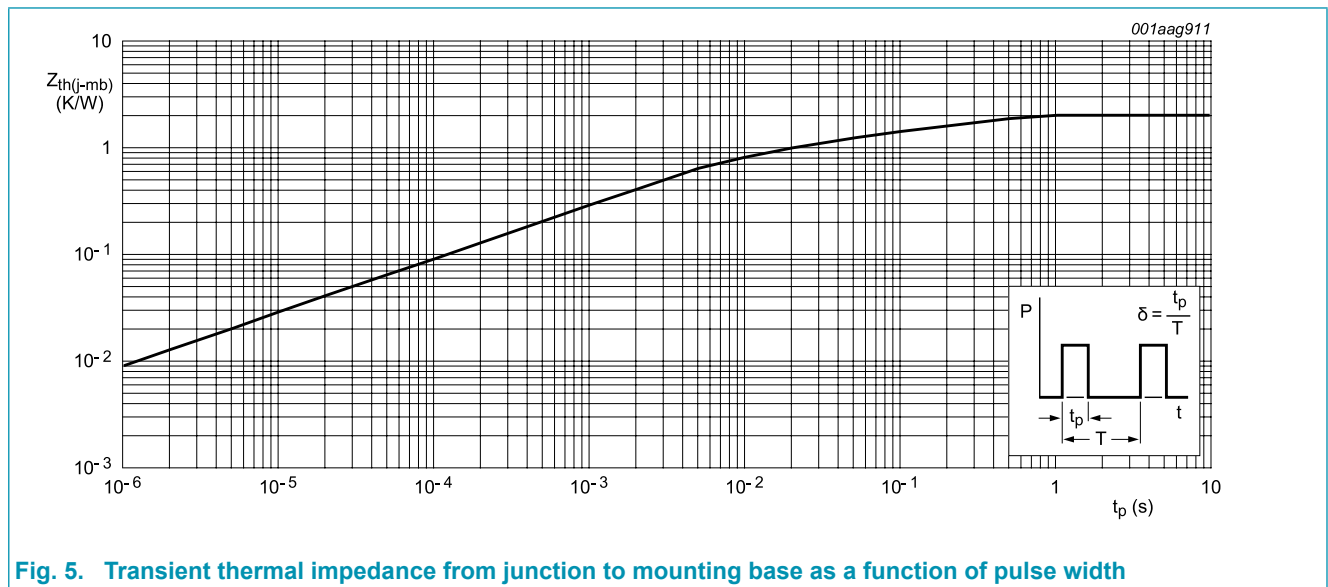
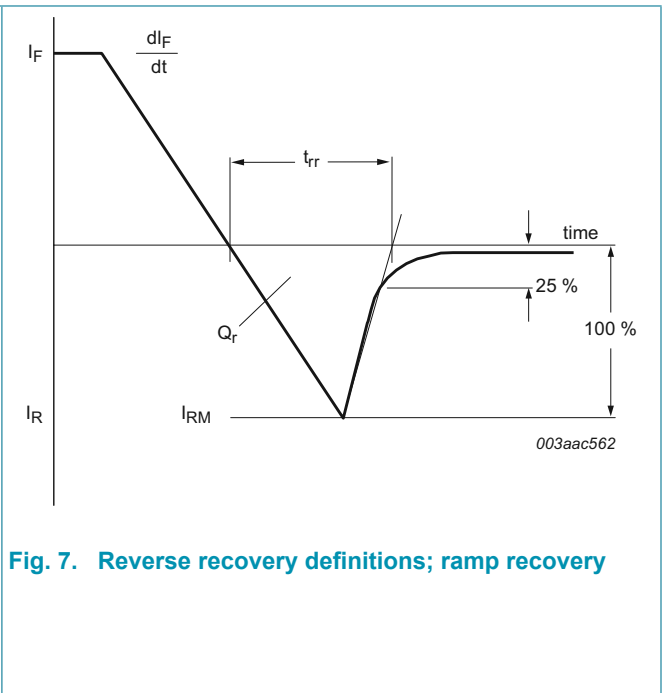
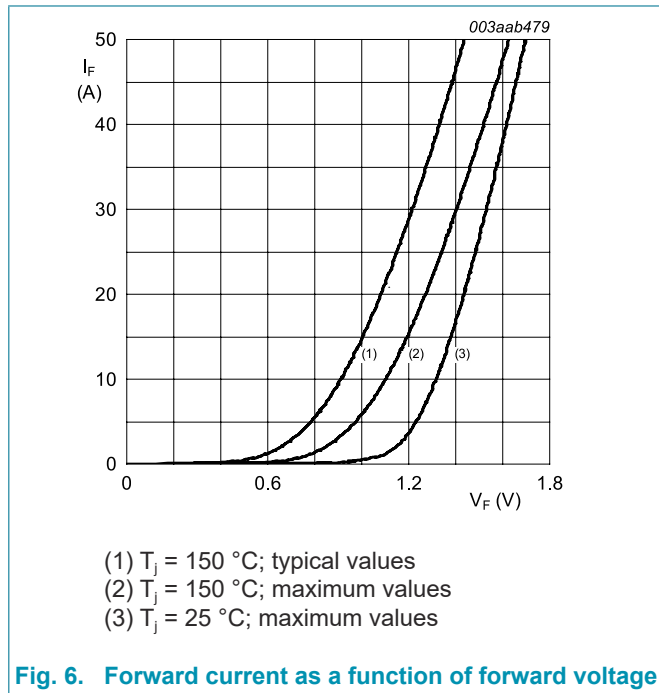


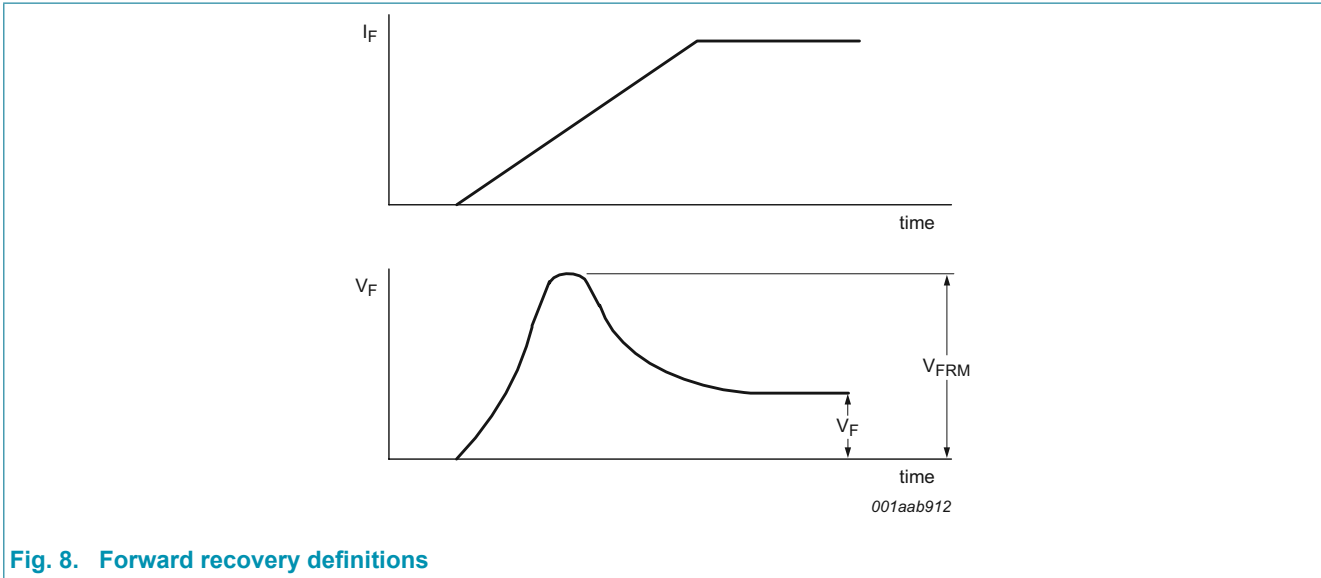
Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse width

### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 15 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 6}$	-	1.17	1.38	V
		$I_F = 15 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{ Fig. 6}$	-	1	1.2	V
$I_R$	reverse current	$V_R = 600 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	5	50	$\mu\text{A}$
		$V_R = 600 \text{ V}; T_j = 100 \text{ }^\circ\text{C}$	-	0.2	0.8	mA
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 2 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 20 \text{ A}/\mu\text{s}; \text{ Fig. 7}$	-	40	70	nC
$t_{rr}$	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 7}$	-	50	60	ns
$I_{RM}$	peak reverse recovery current	$I_F = 10 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s}; T_j = 100 \text{ }^\circ\text{C}; \text{ Fig. 7}$	-	3	5.2	A
$V_{FR}$	forward recovery voltage	$I_F = 10 \text{ A}; dI_F/dt = 10 \text{ A}/\mu\text{s}; \text{ Fig. 8}$	-	3.2	-	V



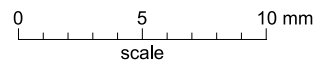
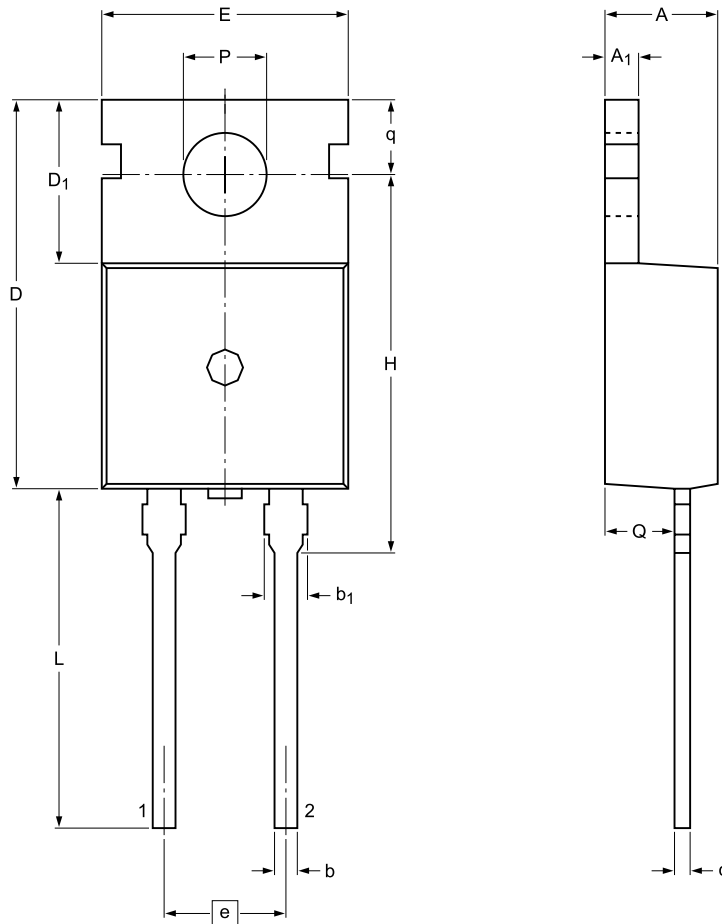


**Fig. 8. Forward recovery definitions**

### 11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC

SOD59



Dimensions

Unit	A	A <sub>1</sub>	b	b <sub>1</sub> (1)	c	D	D <sub>1</sub>	E	e	H	L	P	Q	q
max	4.7	1.40	0.95	1.7	0.65	15.8	6.8	10.30	5.08	16.25	15.0	3.80	2.6	2.9
nom									(REF)					
min	4.3	1.15	0.70	1.3	0.45	15.6	6.4	9.65		15.70	12.5	3.65	2.2	2.7

Note

1. Protruded dambar are included in the dimension.

sod059\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD59	2-lead TO-220AC				09-08-25 12-11-27



## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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